

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listing, of claims in the application:

**Listing of Claims:**

What is claimed is:

Claim 1 (original): An air bridge produced by:

depositing one or more circuit components on a substrate;

depositing a sacrificial material over at least a portion of the circuit components;

depositing a crossover circuit trace over the sacrificial material, the crossover circuit trace crossing over the circuit components; and

thermally decomposing the sacrificial material.

Claim 2 (withdrawn)

Claim 3 (original): The air bridge of claim 1, wherein the sacrificial material comprises polynorbornene.

Claim 4 (original): The air bridge of claim 1, wherein the one or more circuit components comprise a circuit trace.

**Claim 5 (original):** The air bridge of claim 4, wherein the circuit trace comprises a signal trace.

**Claim 6 (original):** The air bridge of claim 4, wherein the circuit trace comprises a ground trace.

**Claim 7 (original):** The air bridge of claim 4, wherein the circuit trace comprises a power trace.

**Claim 8 (original):** The air bridge of claim 1, wherein the crossover circuit trace comprises a signal trace.

Claims 9 – 20 (canceled)

**Claim 21 (new):** An air bridge produced by:

depositing one or more circuit components on a substrate;  
depositing a sacrificial material over at least a portion of the circuit components;  
depositing a crossover circuit trace over the sacrificial material, the crossover circuit trace crossing over the circuit components and being directly supported by the substrate on opposite sides of the sacrificial material; and  
thermally decomposing the sacrificial material.

**Claim 22 (new):** The air bridge of claim, wherein depositing a sacrificial material comprises depositing the sacrificial material in a manner causing the sacrificial material to be dome shaped.

**Claim 23 (new):** The air bridge of claim 21, wherein the sacrificial material comprises polynorbornene.

**Claim 24 (new):** The air bridge of claim 21, wherein the one or more circuit components comprise a circuit trace.

**Claim 25 (new):** The air bridge of claim 24, wherein the circuit trace comprises a signal trace.

**Claim 26 (new):** The air bridge of claim 24, wherein the circuit trace comprises a ground trace.

**Claim 27 (new):** The air bridge of claim 24, wherein the circuit trace comprises a power trace.

**Claim 28 (new):** The air bridge of claim 21, wherein the crossover circuit trace comprises a signal trace.